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Product Change Notification - KMIO-06TADJ110

Date: 01 Dec 2016
Product Category: 8-bit Microcontrollers
Notification subject: CCB 2724 Final Notice: Qualification of G700HA mold compound for selected products available on 80L TQFP (12x12 mm) package at MTAI assembly site.
Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of G700HA mold compound for selected products available in 80L TQFP (12x12 mm) package at MTAI assembly site.

Pre Change:

Assembled at MTAI assembly site using SG-8300ECM mold compound.

Post Change:

Assembled at MTAI assembly site using G700HA or SG-8300ECM mold compound.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MTAI	MTAI
Wire material	Au wire	Au wire
Die attach material	3280/8006NS	3280/8006NS
Molding compound material	SG-8300ECM	G700HA or SG-8300ECM
Lead frame material	C7025	C7025

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying G700HA mold compound at MTAI assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:
January 1, 2017 (Date code :1701)

NOTE: Please be advised that after the estimated first ship date, customers may receive pre and post change parts.

Time Table Summary:

	Oct 2016				->	Dec 2016					Jan 2017					
Workweek	41	42	43	44		49	50	51	52	53	1	2	3	4	5	
Initial PCN Issue Date		X														
Qualification Report Availability						X										
Final PCN Issue Date						X										
Estimated Implementation Date											X					

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
October 10, 2016: Issued initial notification.
December 01, 2016: Issued final notification. Attached the qualification report. Provided an estimated first ship date to be on January 1, 2017.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):
[PCN_KMIO-06TADJ110_Affected CPN.pdf](#)
[PCN_KMIO-06TADJ110_Qual_Report.pdf](#)
[PCN_KMIO-06TADJ110_Affected CPN.xlsx](#)

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KMIO-06TADJ110- Qualification of G700HA mold compound for selected products available on 80L TQFP (12x12 mm) at MTAI assembly site.

Affected Catalog Part Number (CPN)

PCN_KMIO-06TADJ110
CATALOG_PART_NBR
PIC18F86J72-I/PT
PIC18F86J72T-I/PT
PIC18F87J72-I/PT
PIC18F87J72T-I/PT